

W-GM-4200

Wafer Edge Grinding Machine

- Best Seller Machine W-GM-Series
- Improve the Space Efficiency by the Compact Design
- Highly Accurate Grinding by the Synchronized X · Y · θ Support Control
- Easy Operation by Touch Panel
- Measuring of Grinding Result and Automatic Correction



TOKYO SEIMITSU CO., LTD.

Specification of W-GM-4200

Basic Specification		
Wafer Size	$\phi 2'' \sim \phi 6'' / \phi 4'' \sim \phi 8''$	
Wafer Thickness	0.4 ~ 1.0mm (Standard)	
Wafer Type	OF, CF $\times 2$ (<1/2 OF), Notch (Option)	
Grinding Unit	2-stage	
Periphery Grinding Wheel	OD (Groove)	$\phi 200\text{mm}$
	OD (Periphery)	$\phi 202\text{mm}$
	ID	$\phi 30\text{mm}$
	Flange Thickness	20mm
Spindle frequency ($\phi 202$)	4000rpm	
Grinding Speed	Periphery, OF and notch can be set individually	
Periphery Grinding Spindle	$\phi 5 \sim \phi 8$: Built-in motor	
	$\phi 2 \sim \phi 6$: Belt drive by magnet motor	
Operation Panel	12" color LCD panel with touch sensor	
Signal Tower	3-color Indicator	
Dimensions	2115 (W) x 1410 (D) x 2000 (H) mm	
Weight	Approx. 3000kg	
Mechanical Specification		
Grinding Table X, Y, Z-axis	Resolution	1 μm
	Resolution	0.001°
Grinding Table θ -axis	Driving System	AC Servo Motor etc
	Loading System	Chuck Loading (Upper Surface)
Transfer Unit	Cleaning System	Spin Cleaning
	Drying System	Dry Air
Loader Unit	Type	Cassette Carrier Type
	Number of Cassette	4C
Measuring Unit Specification		
Wafer Thickness Measurement	Resolution	1 μm
	Repeatability	Within $\pm 2 \mu\text{m}$
	Accuracy	
	Measuring Type	Contact Type or Non Contact Type
Non-contact Alignment System	Measuring Equipment	Contact Type: Accretech MINIAX (Moire Scale) Non Contact Type: Accretech CADICOM
	Type	Laser System
Non-contact Alignment System	Resolution	1 μm
	Centering Accuracy	Within $\pm 50 \mu\text{m}$

ACCRETECH

Japan / Head Office
 Tokyo Seimitsu Co., Ltd.
 2968-2, Ishikawa-machi, Hachioji-shi, Tokyo, 192-8515 Japan
 TEL: (042) 642-1701 FAX: (042) 642-1798
<https://www.accretech.jp/>

Please contact us.



● We reserve the right to change the contents of this catalog, including product specifications, without notice when products are updated.